

In the Specification

The following is a marked-up version of the specification with the language that is underlined (“ ”) being added and the language that contains strikethrough (“”) being deleted:

Page 1, lines 1 through 2

CONNECTION ARRANGEMENTS FOR ELECTRICAL DEVICES

CROSS-REFERENCE TO RELATED APPLICATION

This application is a continuation of copending U.S. utility application entitled, “Connection Arrangements for Electrical Devices,” having ser. no.09/759,952, filed January 12, 2001, which is entirely incorporated herein by reference.

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An example construction of the electrical device 10 having been provided above, a first connection arrangement will now be discussed with reference to FIG. 5. As indicated in this figure, one or more electrical devices 10 can be mounted to a PCB 26 in the first connection arrangement. The PCB 26 includes a plurality of contacts 28 (*e.g.*, contact ~~paeks~~ pads) formed thereon that can be electrically connected with the various contact terminals 24 of the electrical device 10. Although a particular contact arrangement is shown in FIG. 5, it is to be understood that these contacts are shown only for purposes of example. In the first connection arrangement, electrical connections are made through a plurality of conductor members 30. By way of example, these conductor members 30 can comprise bond wires that are formed with wire bonding techniques. As indicated in FIG. 5, each of the conductor members 30 extends from a

particular contact terminal 24 provided on the ledges 20 of the electrical device 10, ~~extend~~ extends down the side of the device, and ~~connect~~ connects to a particular contact 28 provided on the surface of the PCB 26. Although each of the conductor members 30 is shown extending downwardly from the electrical devices 10 in the same parallel direction, it is to be understood that the orientation of the conductor members depends upon the location of the contacts 28 provided on the PCB 26 and the location of the memory devices relative to the PCB.

FIG. 6 illustrates a second connection arrangement for the electrical device 10. As indicated in this figure, the electrical device 10 is inverted (relative to the orientation shown in FIG. 5) prior to connection such that the top layer 14 of the device faces the PCB 32. In the second connection arrangement, the PCB 32 includes at least one recess or cavity 34 36 that is adapted to receive the electrical device 10. As with the arrangement shown in FIG. 5, the PCB 32 includes a plurality of contacts 34 that are adapted to electrically connect with the contact terminals 24 (FIG. 1) of the electrical device 10.